

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE (π -MOSV)

2SK2750

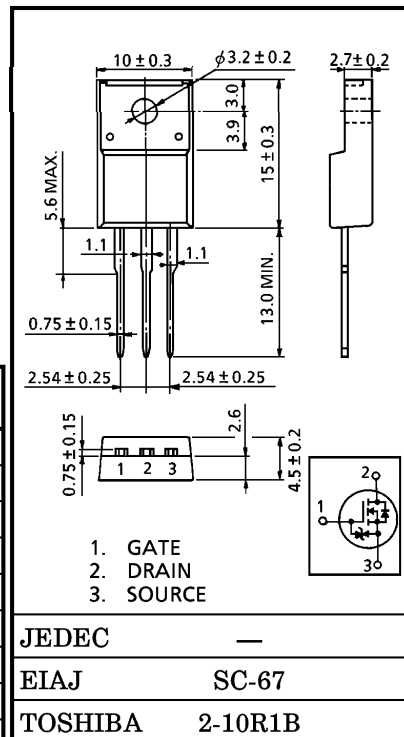
HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS
 CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE APPLICATIONS

INDUSTRIAL APPLICATIONS
 Unit in mm

- Low Drain-Source ON Resistance : $R_{DS(ON)} = 1.7\Omega$ (Typ.)
- High Forward Transfer Admittance : $|Y_{fs}| = 3.0S$ (Typ.)
- Low Leakage Current : $I_{DSS} = 100\mu A$ (Max.) ($V_{DS} = 600V$)
- Enhancement-Mode : $V_{th} = 2.0 \sim 4.0V$ ($V_{DS} = 10V, I_D = 1mA$)

MAXIMUM RATINGS ($T_a = 25^\circ C$)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Drain-Source Voltage	V_{DSS}	600	V
Drain-Gate Voltage ($R_{GS} = 20k\Omega$)	V_{DGR}	600	V
Gate-Source Voltage	V_{GSS}	± 30	V
Drain Current	DC	I_D	3.5 A
	Pulse	I_{DP}	14 A
Drain Power Dissipation ($T_c = 25^\circ C$)	P_D	35	W
Single Pulse Avalanche Energy**	E_{AS}	201	mJ
Avalanche Current	I_{AR}	3.5	A
Repetitive Avalanche Energy*	E_{AR}	3.5	mJ
Channel Temperature	T_{ch}	150	$^\circ C$
Storage Temperature Range	T_{stg}	$-55 \sim 150$	$^\circ C$



Weight : 1.9g

HERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	$R_{th(ch-c)}$	3.57	$^\circ C / W$
Thermal Resistance, Channel to Ambient	$R_{th(ch-a)}$	62.5	$^\circ C / W$

Note ;

- * Repetitive rating ; Pulse Width Limited by Max. junction temperature.
- ** $V_{DD} = 90V$, Starting $T_{ch} = 25^\circ C$, $L = 28.8mH$, $R_G = 25\Omega$, $I_{AR} = 3.5A$

**This transistor is an electrostatic sensitive device.
 Please handle with caution.**

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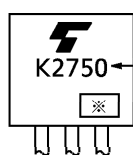
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage Current		IGSS	VGS = ±25V, VDS = 0V	—	—	±10	μA
Gate-Source Breakdown Voltage		V (BR) GSS	IG = ±10μA, VDS = 0V	±30	—	—	V
Drain Cut-off Current		IDSS	VDS = 600V, VGS = 0V	—	—	100	μA
Drain-Source Breakdown Voltage		V (BR) DSS	ID = 10mA, VGS = 0V	600	—	—	V
Gate Threshold Voltage		Vth	VDS = 10V, ID = 1mA	2.0	—	4.0	V
Drain-Source ON Resistance		RDS (ON)	VGS = 10V, ID = 1.8A	—	1.7	2.2	Ω
Forward Transfer Admittance		Yfs	VDS = 10V, ID = 1.8A	2.0	3.0	—	S
Input Capacitance		Ciss	VDS = 25V, VGS = 0V, f = 1MHz	—	800	—	pF
Reverse Transfer Capacitance		Crss		—	6	—	
Output Capacitance		Coss		—	65	—	
Switching Time	Rise Time	tr	<p>VGS 10V 0V</p> <p>ID = 1.8A</p> <p>VOUT</p> <p>50Ω</p> <p>RL = 111Ω</p> <p>VDD ≐ 200V</p> <p>VIN : tr, tf < 5ns, Duty ≤ 1%, tw = 10μs</p>	—	15	—	ns
	Turn-on Time	ton		—	50	—	
	Fall Time	tf		—	15	—	
	Turn-off Time	t _{off}		—	85	—	
Total Gate Charge (Gate-Source Plus Gate-Drain)		Qg	VDD ≐ 400V, VGS = 10V, ID = 3.5A	—	20	—	nC
Gate-Source Charge		Qgs		—	10	—	
Gate-Drain (“Miller”) Charge		Qgd		—	10	—	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	IDR	—	—	—	3.5	A
Pulse Drain Reverse Current	IDRP	—	—	—	14	A
Diode Forward Voltage	VDSF	IDR = 3.5A, VGS = 0V	—	—	-1.7	V
Reverse Recovery Time	t _{rr}	IDR = 3.5A, VGS = 0V	—	400	—	ns
Reverse Recovery Charge	Q _{rr}	dIDR / dt = 100A / μs	—	2.6	—	μC

MARKING

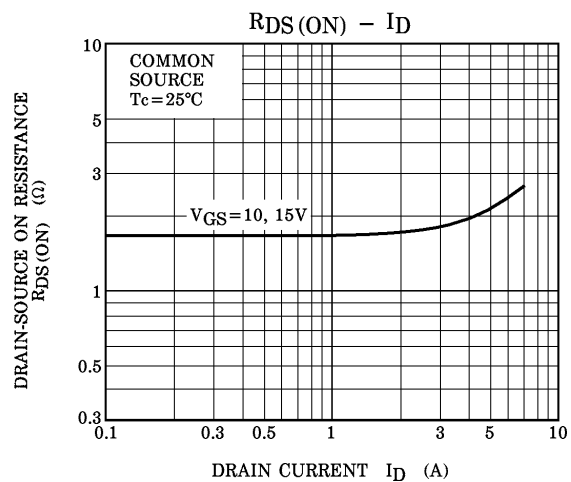
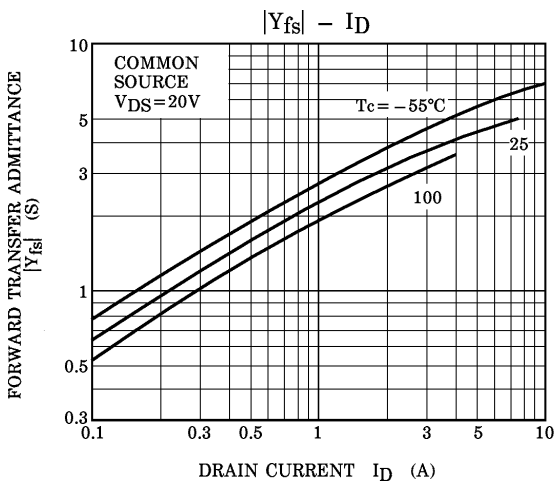
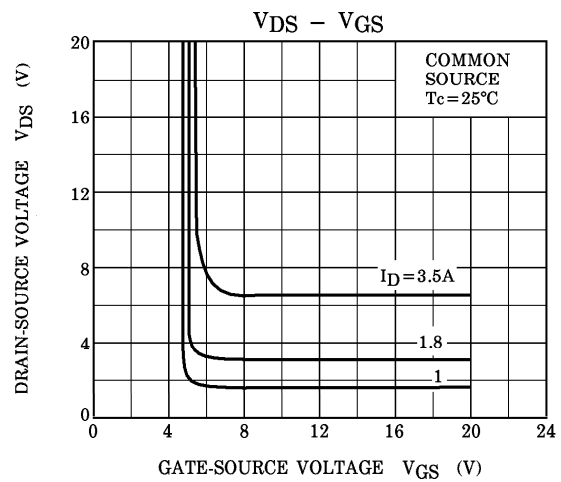
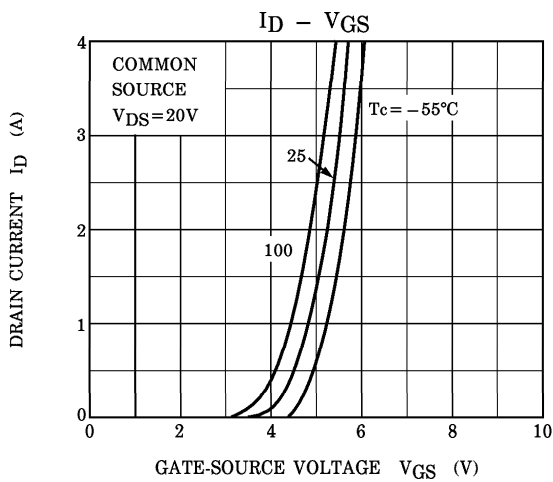
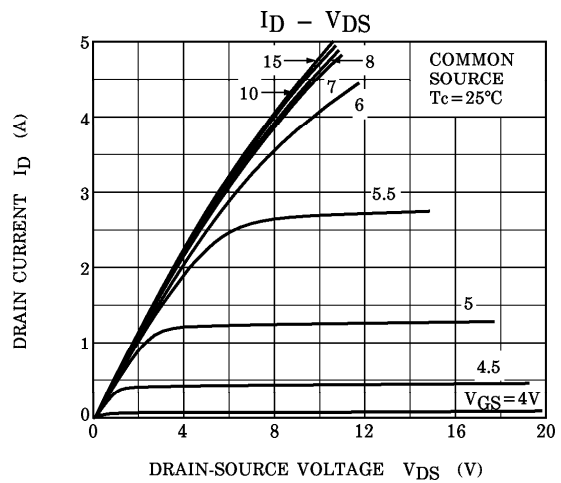
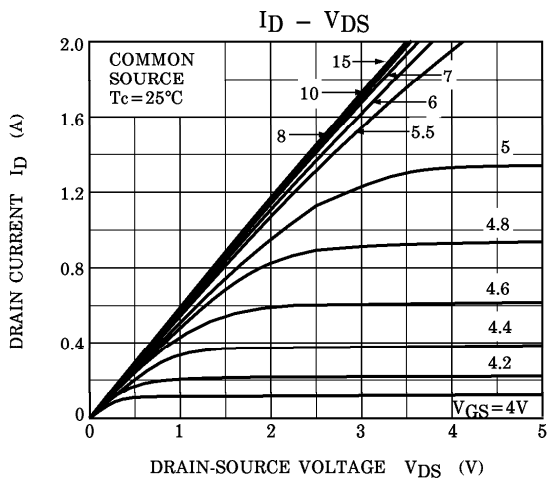


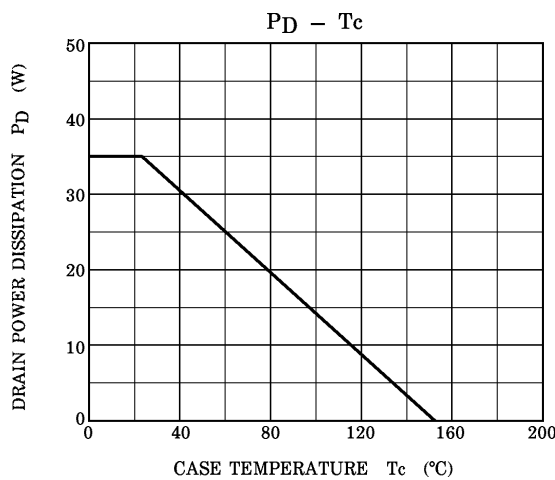
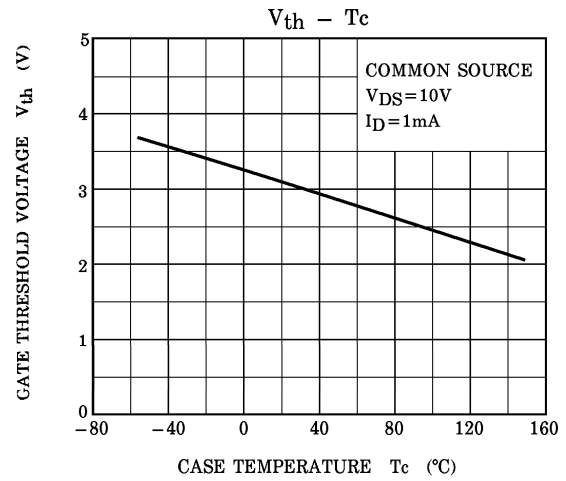
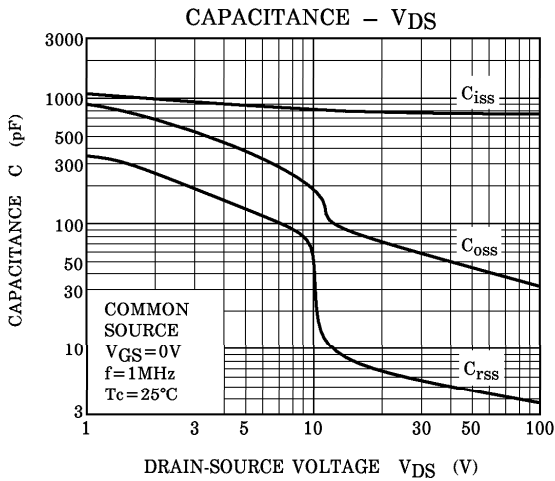
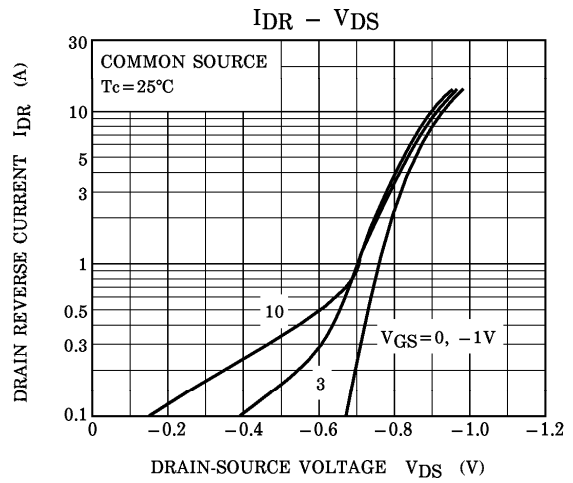
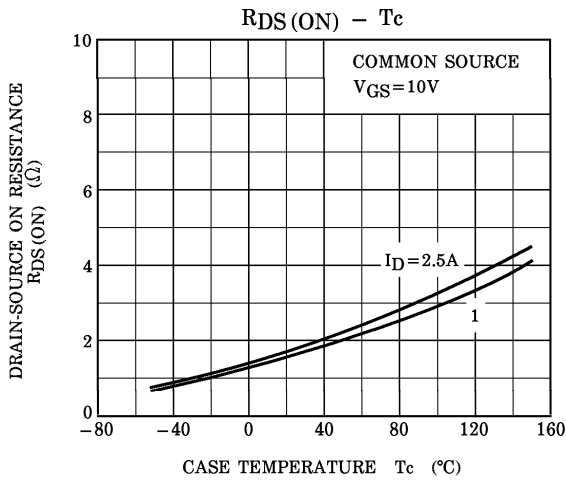
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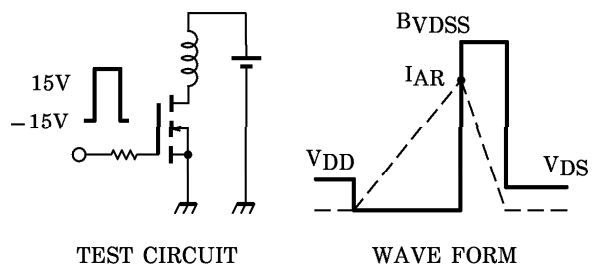
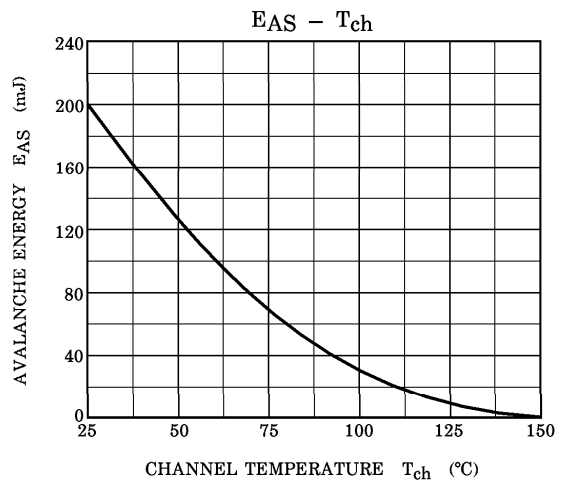
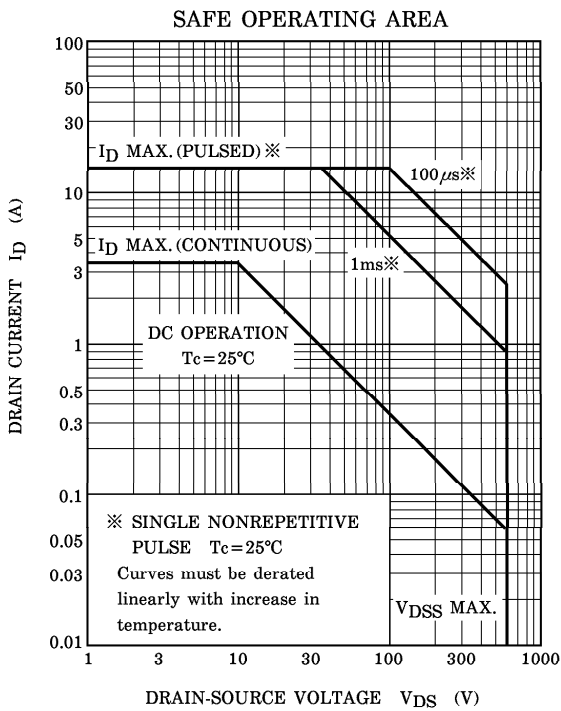
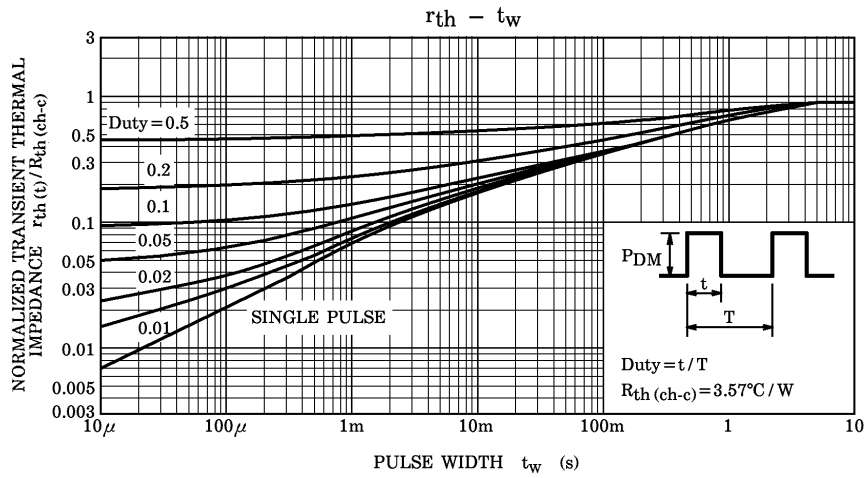
※ Lot Number

□ □ — Month (Starting from Alphabet A)

— Year (Last Number of the Christian Era)







Peak $I_{AR} = 3.5A$, $R_G = 25\Omega$ $E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - V_{DD}} \right)$
 $V_{DD} = 90V$, $L = 28.8mH$